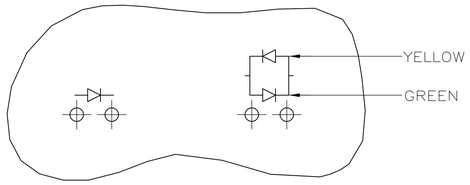
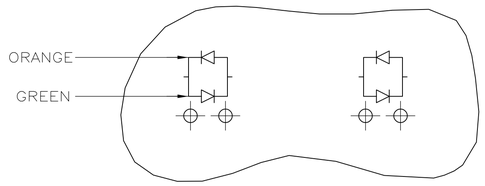
LOC	DIST
AA	00

REVISIONS

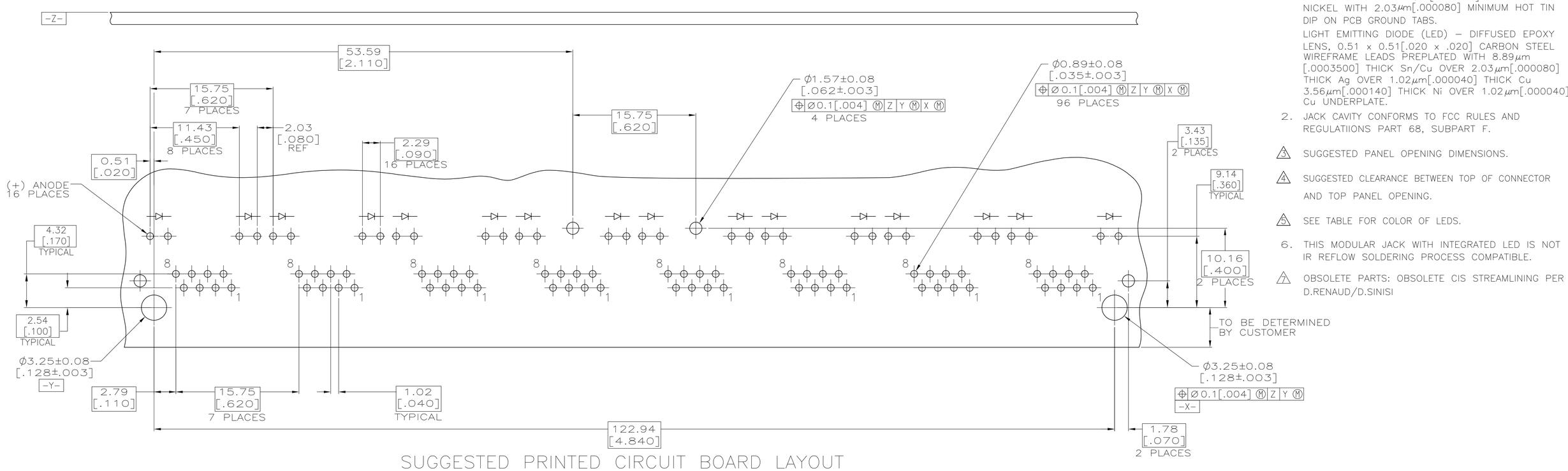
P	LTR	DESCRIPTION	DATE	DWN	APVD
	C	ECR-08-031889	16DEC2008	JY	SY
	C1	REVISED PER ECO-09-024927	09NOV09	KK	AEG



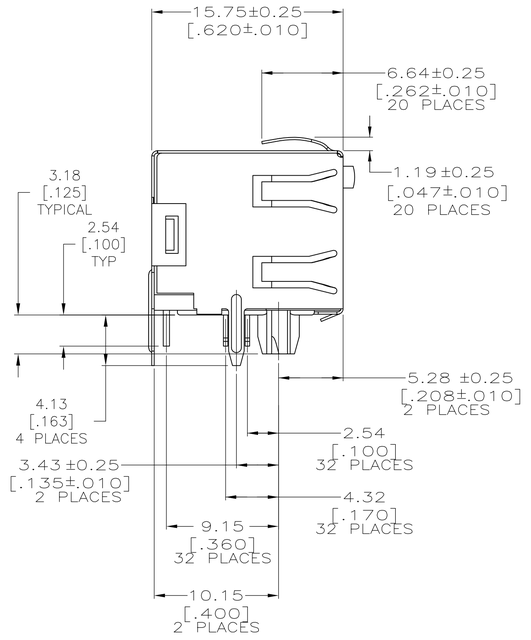
LED CURRENT DIAGRAM
5406967-8 ONLY

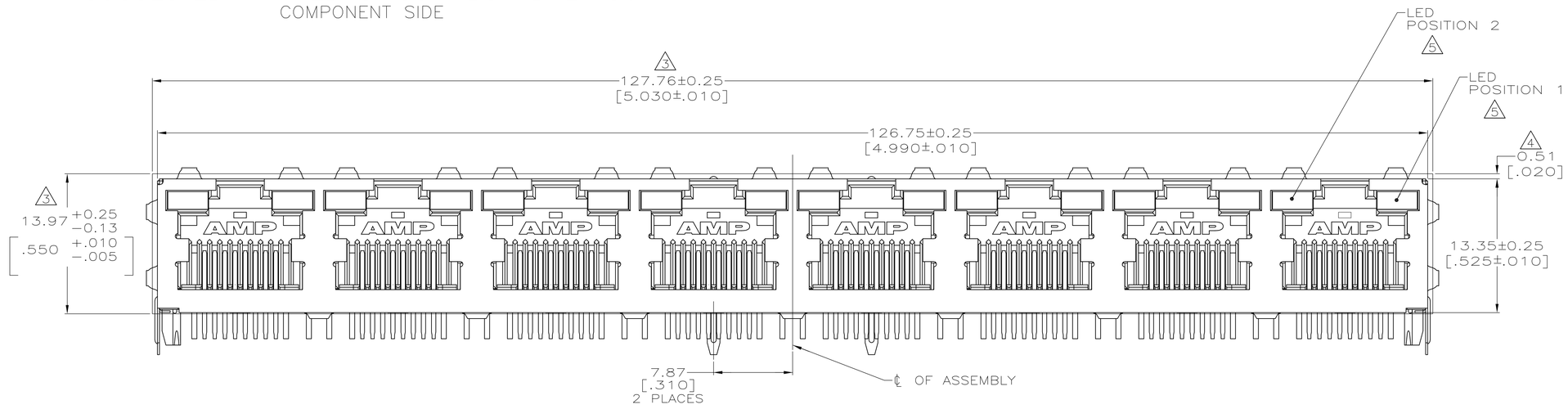


LED CURRENT DIAGRAM
7 ~~5406967-7~~ ONLY



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
COMPONENT SIDE





	GREEN	GREEN/YELLOW	~~5406967-8~~
OBSOLETE 7	ORANGE/GREEN	ORANGE/GREEN	~~5406967-7~~
	YELLOW	YELLOW	~~5406967-6~~
	GREEN	GREEN	~~5406967-5~~
	GREEN	YELLOW	5406967-4
OBSOLETE 7	YELLOW	–	~~5406967-3~~
	–	GREEN	~~5406967-2~~
	YELLOW	GREEN	~~5406967-1~~
	POSITION 2	POSITION 1	PART NUMBER
	INDICATOR COLOR FOR EACH HOUSING		

1. MATERIAL:
HOUSING – HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
TERMINALS – 0.36[.014] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm [.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE.
SHIELD – 0.196[.0077] THICK COPPER ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
LIGHT EMITTING DIODE (LED) – DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89µm [.0003500] THICK Sn/Cu OVER 2.03µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu 3.56µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE.
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIIONS PART 68, SUBPART F.
3. SUGGESTED PANEL OPENING DIMENSIONS.
4. SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
5. SEE TABLE FOR COLOR OF LEDS.
6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
7. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± –
1 PLC ± –
2 PLC ± 0.25[.01]
3 PLC ± 0.13[.005]
4 PLC ± –
ANGLES ± –

MATERIAL SEE NOTE 1
FINISH SEE NOTE 1

DWN	B. LATTUCA 22SEPT05
CHK	J. WESTMAN 22SEPT05
APVD	S. FLICKINGER 22SEPT05
PRODUCT SPEC	108-1163-4
APPLICATION SPEC	114-2154
WEIGHT	–
CUSTOMER DRAWING	

Tyco Electronics
Tyco Electronics Corporation
Harrisburg, PA 17105-3608

NAME: INVERTED MODULAR JACK ASSEMBLY, 1X8, SHIELDED, BOTTOM TAB, PANEL GROUND, LED

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A1	00779	C-5406967	–

SCALE 4:1 SHEET 1 OF 1 REV C1